



S/09/382,929

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PATENT  
C. MooreIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar  
Serial No.: 09/382,929  
Filed: August 25, 1999  
Title: PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES

Examiner: David E. Graybill  
Group Art Unit: 2827  
Docket: 303.603US1

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant requests that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicant with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), please charge Deposit Account No. 19-0743 in the amount of \$180.00.

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

PAUL A. FARRAR

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
P.O. Box 2938  
Minneapolis, MN 55402  
(612) 371-2109

Date September 16, 2002

By

Danny J. Pady  
Danny J. Pady

Reg. No. 35,635

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 16 day of September, 2002.

Name

Tina Kohout

Signature

Z. Kohout